(B) BONDED WAFERS

ADVANTAGE - ISLAND SIZE NOT LIMITED AS IN D.I. (SPACE)

DISADVANTAGE - COST, REQUIRES 2 WAFERS.

BONDED WAFER PROCESS

1.) OXIDIZE TWO WAFERS

2.) BOND WAFERS

3.) OXIDIZE WAFERS

4.) GRIND AND POLISH WAFER 1.
   - ADD EPI STEP IF DESIRED.